COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP20981</th>
<th>REV: A</th>
<th>SVN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>TID #: N/A</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 6/19/2017 5:01:26 PM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
</tr>
</tbody>
</table>
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